



# International Microwave Workshop Series on Silicon Integration for Communication Techniques

IMWS SICOMTEC 2013 October 29-30, 2013 - Grenoble France

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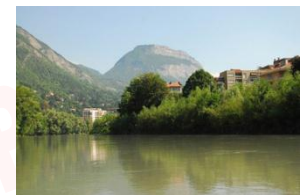
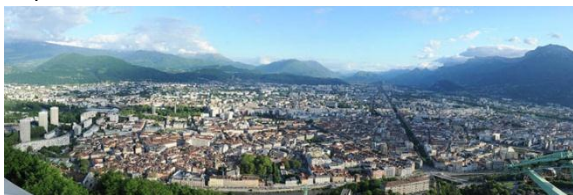
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## Call for Papers

**IEEE International Microwave Workshop Series on Silicon Integration for Communication Techniques 2013** is an initiative promoted by the MTT-S Transnational Committee, to complement the existing workshops of the MTT-S International Microwave Symposia. The purpose of this platform is to boost and promote MTT-S technical and educational activities as well as MTT-S international exchanges and collaborations. IMWS SICOMTEC 2013 is organized by the **Institute of Microelectronics, Electromagnetism and Photonics (IMEP-LAHC)** under the auspices of IEEE and IEEE Microwave Theory and Techniques Society (MTT-S).

**IMWS SICOMTEC 2013** will be held on **October 29-30, 2013** in Grenoble France, capital of the French Alps. The workshop venue is the micro and nanotechnologies innovation campus (MINATEC). It is easy reachable by walk from the train station. The International Lyon Airport is 1 hour far with frequent shuttles between the airport and the train station.



## Areas of Interest

- Systems architecture
- Active and passive mmW integrated circuits (addressed technologies Si, Si-Ge, SOI)
- Microwave and mmW photonic circuits
- mmW-RFID & Integrated antennas solutions
- Packaging Techniques, 3D integration and TSV enabling circuits, High speed interconnects
- Measurement and characterization techniques
- Numerical and CAD techniques

## Submission Information

Submissions must be electronic in PDF (no hard copies accepted). All papers must be written in English and limited to four pages. Final papers must conform the IMWS template and should be an IEEE Xplore® compliant PDF file since accepted and presented papers will be published on-line. Please visit <http://sicomtec2013.sciencesconf.org> for further details and submission

## Important Dates

**Paper Submission**

**April 30th, 2013**

**Notification of Acceptance**

**June 30th, 2013**

**Final Paper Due**

**July 15th, 2013**

